

Federal Communications Commission
Authorization and Evaluation Division
7435 Oakland Mills Rd.
Columbia, MD. 21046

Date: Feb. 29, 2000

Attention: Authorization and Evaluation Division

Subject: RFI related modifications incorporated into unit with
COLOR MONITOR - FCC ID: IJE796

Dear Sirs:


This letter serves as our declaration that all modifications listed below were implemented in the sample submitted for testing. We further declare that the same modifications will be implemented into all production units to enhance compliance of the units to FCC limits.

The modifications include the following:

- 1) Added two ferrite cores on the video cable, one outside and one inside the monitor. (see photo 2 & 5)
- 2) Added a metal cover on the rear side of CRT board and it was connected to chassis by 16 ground wires. (see photo 4, 5 & 6)
- 3) Added a ferrite core on the harness of two ground wires. (see photo 8)
- 4) Added a ferrite core on the ground wire with one turn. (see photo 8)
- 5) Added a ferrite core on the ground wire with three turns. (see photo 8)
- 6) Added a ferrite core on the safety ground wire with three turns. (see photo 7)
- 7) Added a ferrite core on the harness of G2 and focus wires with two turns. (see photo 9)
- 8) Added a ferrite core on the wires connected between mainboard and power connector of ext. speaker with one turn. (see photo 9)
- 9) Added a ferrite core on the wire connected between CRT and CRT board with three turns. (see photo 7)
- 10) Added a ferrite core on the wire connected between mainboard and CRT board with 2 turns. (see photo 7)
- 11) Added a ferrite core on the wire connected between mainboard and CRT board with 2 turns. (see photo 7)
- 12) Added a ferrite core on the Mic. cable with two turns. (see photo 7)
- 13) Added 3 capacitors, 3 bead cores and 1 resistor on the solder side of mainboard for EMI. They will be built into the component side after circuit re-layout. (see photo 10)
- 14) Added 4 capacitors and 2 bead cores on the solder side of CRT board for EMI. They will be built into the component side after circuit re-layout. (see photo 12)

If you have any further questions or comments regarding the above, please don't hesitate to contact Mr. Mike Su of ADT Lab. at fax No.: 886-2-2602-2943 or
E-mail: mike@mail.adt.com.tw

Sincerely yours,

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W. H. Chen/ Engineer
PROVIEW ELECTRONICS (TAIWAN) CO., LTD.

CC. Mr. Harris W. Lai - Advance Data Technology Corporation